

RZ/N2H Group

Modbus Sample Program Package Guide

Introduction

This guide describes the package structure and explains how to use the Modbus sample programs for the RZ/N2H Group.

Target Device

RZ/N2H Group

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1. Overview

This guide describes the package structure and the features of the sample programs.

1.1 Abbreviations / Definitions

Table 1.1 Abbreviations / Definitions

Index	Abbreviations / Definitions	Description
1	IP	Internet Protocol
2	TCP	Transmission Control Protocol
3	USB	Universal Serial Bus
4	PC	Personal Computer
5	SW	Switch
6	EWARM	Embedded Workbench® for Arm
7	LED	Light Emitting Diode
8	Wireshark	A free packet capture tool for monitoring LAN traffic
9	Client	Modbus TCP client / Requesting device
10	Server	Modbus TCP server / Responding device
11	MAC	Media Access Control
12	LAN	Local Area Network
13	DHCP	Dynamic Host Configuration Protocol
14	PHY	Physical Layer
15	lwIP	Lightweight IP
16	RS-485	Serial communication standard based on TIA/EIA-485
17	SBOM	Software Bill of Materials

1.2 References

1.2.1 About RZ/N2H

Technical information about Modbus is available from the Modbus Organization. Technical documentation for the RZ/N2H Group is available from Renesas.

Table 1.2 Technical References for RZ/N2H

Document Type	Document Title	Description	Document No.
User's Manual	RZ/T2H and RZ/N2H Group User's Manual Hardware	RZ/T2H and RZ/N2H Group User's Manual Hardware	r01uh1039ej****
Datasheet	RZ/T2H and RZ/N2H Group Datasheet	RZ/T2H and RZ/N2H Group Datasheet	r01ds0426ej****
Getting Started	RZ/T2, RZ/N2 Group FSP Getting Started Guide	RZ/T2, RZ/N2 Group Flexible Software Package Getting Started Guide	r01an6434ej****
User's Manual	RZ/N2H Evaluation Board User's Manual	RZ/N2H Evaluation Board User's Manual	r20ut5522ej****
Reference Guide	Modicon Modbus Protocol Reference Guide Rev.J	Modbus Protocol Reference Guide Rev.J	PI-MBUS-300 Rev. J
Specification	Modbus Application Protocol Specification V1.1b3	Modbus Application Protocol Specification V1.1b3	v1.1b3

2. Features

This package includes firmware for the Modbus communication stack optimized for Renesas RZ/N2H series processors.

This package includes the following features:

- Comprehensive Modbus Protocol Support:
 - Modbus TCP (Ethernet / Server)
 - Modbus RTU (Serial / Client and Server)
 - Modbus ASCII (Serial / Client and Server)
- Modbus Gateway Functions:
 - Transparent bridging between Modbus TCP and Modbus RTU
 - Protocol conversion and request routing between the connected Modbus networks
- Supported Register and Coil Operations:
 - Read / Write Holding Registers
 - Read / Write Coils
 - Read Discrete Inputs
 - Read Input Registers
- I/O Functions:
 - DIP switch input
 - LED output

2.1 Package Folder Structure

After extracting the package archive, the folders and files shown in Table 2.1 are created.

Table 2.1 Sample Folder and File Structure

IDE project folder for Modbus TCP	Description
r01an7607xx0410-rzn2h-modbus-package	RZN2H Modbus Sample Package
├── RZN2H_Modbus_EVB_rev0410	Archive for the RZ/N2H Evaluation Board
│ ├── Modbus_tcp_lwip	Modbus_tcp_lwip folder
│ │ ├── common	Common folder
│ │ │ ├── oss	Lightweight TCP/IP stack for embedded systems
│ │ │ └── renesas	Renesas-specific Modbus application code
│ │ └── project	IDE project folder for Modbus TCP
│ │ ├── CR52_dual	CR52 project folder
│ │ │ ├── e2studio	e ² studio project
│ │ │ └── ewarm	EWARM project
│ │ └── CR52-CA55_dual	CR52-CA55 project folder
│ │ ├── e2studio	e ² studio project
│ │ └── ewarm	EWARM project
│ ├── Modbus_serial	Modbus_serial folder
│ │ ├── common	Common folder
│ │ │ └── renesas	Renesas-specific Modbus application code
│ │ └── project	IDE project folder for serial
│ │ ├── CR52_dual	CR52 project folder
│ │ │ ├── e2studio	e ² studio project
│ │ │ └── ewarm	EWARM project
│ │ └── CR52-CA55_dual	CR52-CA55 project folder
│ │ ├── e2studio	e ² studio project
│ │ └── ewarm	EWARM project
│ ├── Modbus_gateway	Modbus_gateway folder
│ │ ├── common	Common folder
│ │ │ └── renesas	Renesas-specific Modbus application code
│ │ └── project	IDE project folder for gateway
│ │ ├── CR52_dual	CR52 project folder
│ │ │ ├── e2studio	e ² studio project
│ │ │ └── ewarm	EWARM project
│ │ └── CR52-CA55_dual	CR52-CA55 project folder
│ │ ├── e2studio	e ² studio project
│ │ └── ewarm	EWARM project
└── Modbus_tool	Tool folder
└── SBOM	SBOM folder
└── r01an7607ej0410-rzn2h-modbus-package.pdf	This guide
└── r01an7608ej0410-rzn2h-modbus-tcp.pdf	Application note for Modbus TCP projects
└── r01an7609ej0410-rzn2h-modbus-serial.pdf	Application note for Modbus serial projects
└── r01an7610ej0410-rzn2h-modbus-gateway.pdf	Application note for Modbus gateway projects

3. Requirements (Software and Hardware)

The sample programs were developed and tested using the boards and tools listed below.

3.1 Requirements for this sample package

Table 3.1 Requirements

Category	Name	Version	Description
Board	RZ/N2H Evaluation Board	-	RZ/N2H Evaluation Board Renesas Evaluation Board Kit for RZ/N2H
IDE	Flexible Software Package	V4.1.0	Renesas Flexible Software Package (FSP)
	e ² studio	2026-04.1	
	- GNU ARM Embedded Toolchain	13.3.1.arm-13-24 for CR52	
	- GNU ARM A-Profile (AArch64 bare-metal)	13.2.1.20231009 for CA55	
	IAR Systems	9.60.3	
	- Embedded Workbench for ARM	EWARM_Patch_f or_RZT2H_N2H_rev1.0	
	- patch		
	GNU ARM Embedded Toolchain	13.3.1.arm-13-24 for CR52	
	GNU ARM A-Profile (AArch64 bare-metal)	13.2.1.20231009 for CA55	
Emulator	J-Link™	8.60	SEGGER SEGGER - The Embedded Experts - Downloads - J-Link / J-Trace
Software	ModbusDemoApplication.exe	V1.3	Windows application included with the sample package for exercising and verifying the Modbus sample programs

Revision History

Rev.	Date	Description	
		Page	Summary
2.00	Dec. 23, 2024	-	First edition issued
2.11	Jun. 20, 2025	-	- Added an FSP 2.2 compatibility method - Changed the switch settings for the MP board
3.00	Nov. 28, 2025	-	Added support for RZ/N2 FSP 3.0.0.
4.00	Apr. 10, 2026	-	Added support for RZ FSP 4.0.0.
4.10	Jul. 31, 2026	-	Added support for RZ FSP 4.1.0. Added SBOM support.

Website and Support

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Inquiries

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1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

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